EAST Search History

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
S2	144	basol$-b$.in. and electrochemical adj mechanical	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/04/26 16:31
S3	144	basol$-b$.in. and electrochemical adj mechanical$2	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/04/26 16:39
S5	90	etch$3 with sweep	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/04/27 13:09
S4	27	basol$-b$.in. and electrochemical adj mechanical$2 and temperature	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/04/27 13:09
S6	1	etch$3 with sweep same (suppress$4 accelerat$3)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/04/27 13:25
S9	138	surface adj moiety and (pad sweep)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/04/27 13:34
S8	510	surface adj moiety	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/04/27 13:34
S7	3	polish$3 with sweep same (suppress$4 accelerat$3)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/04/27 13:34
S11	0	surface adj moiety and (pad sweep) and chemical adj mechanical adj polishin	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/04/27 13:38

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S10	110	surface adj moiety and (pad sweep) and (polishing etching removing)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/04/27 13:38
S14	401	temperature with electroplating with copper	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/04/27 13:45
S15	6	("6004880" | "6090239" | "6224737" | "6245676" | "6284121" | "6303014"). PN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/04/27 13:53
S16	2	surface adj moiety and chemical adj mechanical adj polishing and temperature	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/04/27 14:01
S17	134	accelerator with (adsor$5 absor$5) with temperature	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/04/27 14:02
S18	33	accelerator with (adsor$5 absor$5) with temperature and mechanical	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/04/27 14:03
S20	128	accelerator with (adsor$5 absor$5) and ("204" "205" "51" "451").clas.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/04/27 14:10
S21	9	accelerator with (adsor$5 absor$5) same temperature and ("204" "205" "51" "451").clas.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/04/27 14:11
S19	2	accelerator with (adsor$5 absor$5) with temperature and ("204" "205" "51" "451").clas.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/04/27 14:11
S24	8	brighten$3 with (adsor$5 absor$5) same temperature and ("204" "205" "51" "451").clas.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/04/27 14:12

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S23	1	brighten$3 with (adsor$5 absor$5) with temperature and ("204" "205" "51" "451").clas.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/04/27 14:12
S22	0	brighten$2 with (adsor$5 absor$5) with temperature and ("204" "205" "51" "451").clas.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/04/27 14:12
S12	3	surface adj moiety and (pad sweep) and chemical adj mechanical adj polishing	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/04/27 14:16
S26	1050	chelat$3 and chemical adj mechanical adj polishing	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/04/27 14:17
S25	4	surface adj moiety and chemical adj mechanical adj polishing	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/04/27 14:17
S28	19	chelat$3 with temperature and chemical adj mechanical adj polishing	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/04/27 14:18
S27	46986	chelat$3 with temperatureand chemical adj mechanical adj polishing	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/04/27 14:18
S29	19	chelat$3 with temperature and (chemical electrochemical) adj mechanical adj polishing	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/04/27 14:31
S31	61	S30 not S29	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/04/27 14:32
S32	79	sawtooth and ("204" "205" "451"). clas.	US-PGPUB	OR	ON	2006/04/28 15:30

S33	239	(accelerator accelerating brightener brightening) with composition same electroplat$	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/04/28 15:51
S30	80	(chelat$3 accelerator accelerating brightener brightening) with temperature and (chemical electrochemical) adj mechanical adj polishing	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/04/28 15:51
S13	20	("20010015321"|"4080513"|"6004880"|"6090239"|"6224737"|"6245676"|"6284121"|"6303014"|"6344129"|"6534116").PN.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/05/11 10:53
S36	322	electroplat$ with (wafer semiconductor microelectronic microfeature) and (paddle stirring agitating)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/05/11 10:54
S35	272	electroplat$ with (wafer semiconductor microelectronic microfeature) and (paddle stirring)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/05/11 10:54
S34	5384	electroplat$ with (wafer semiconductor microelectronic microfeature)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/05/11 10:54
S37	87	electroplat$ with copper with (wafer semiconductor microelectronic microfeature) and (paddle stirring agitating)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/05/11 10:55
S40	1	"5807165".PN.	USPAT; USOCR	OR	ON	2006/05/11 10:56
S38	29	electroplat$ with copper with (wafer semiconductor microelectronic microfeature) and uzoh.in.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/05/11 10:56

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S43	33	("3421994" | "3511758" | "4302316" | "4532017" | "4626331" | "4793895" | "4821466" | "4861449" | "4934102" | "5078801" | "5167792" | "5168887" | "5225034" | "5240552" | "5449313" | "5464519" | "5492594" | "5516412" | "5522975" | "5534106" | "5543032" | "5567300" | "5575706" | "5620581" | "5624300" | "5637185" | "5685766" | "5744019" | "5755859" | "5793272" | "5807165").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/05/11 10:57
S42	33	("3421994" | "3511758" | "4302316" | "4532017" | "4626331" | "4793895" | "4821466" | "4861449" | "4934102" | "5078801" | "5167792" | "5168887" | "5225034" | "5240552" | "5449313" | "5464519" | "5492594" | "5516412" | "5522975" | "5534106" | "5543032" | "5567300" | "5575706" | "5620581" | "5624300" | "5637185" | "5685766" | "5744019" | "5755859" | "5793272" | "5807165").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/05/11 10:57
S41	104	uzoh.in. and ("204" "205").clas.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/05/11 10:57
S39	84	electroplat$ with (wafer semiconductor microelectronic microfeature) and uzoh.in.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/05/11 10:57
S47	5	("4,110,176" "4,376,685" "4,975,159" "3,770,598" "3,328,273").pn.	USPAT	OR	ON	2006/05/11 11:17
S46	0	("4,110,176" "4,376,685" "4,975,159" "3,770,598" "3,328,273").pn. and accelerant	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/05/11 11:17
S45	0	("4,110,176" "4,376,685" "4,975,159" "3,770,598" "3,328,273").pn. and accelerator	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/05/11 11:17
S44	15	("4,110,176" "4,376,685" "4,975,159" "3,770,598" "3,328,273").pn.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/05/11 11:17

S48	73	205/640-686.ccls. and (brightening brightener)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/05/11 11:45
S51	84	205/640-686.ccls. and (brightening brightener accelerator accelerant accelerating) and copper	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/05/11 11:46
S50	122	205/640-686.ccls. and (brightening brightener accelerator accelerant accelerating)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/05/11 11:46
S49	94	205/640-686.ccls. and (brightening brightener accelerator accelerant)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/05/11 11:46
S1	313	basol$-b$.in.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/05/11 15:09
L2	2	"6921551".pn.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/05/11 15:09
L5	1210	temperature with control$4 same ((wafer adj chuck) (substrate adj support))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/05/11 15:19
L6	88	temperature with control$4 same ((wafer adj chuck) (substrate adj support)) and electroplat$	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/05/11 15:31
L9	14	uzoh.in. and "451".clas.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/05/11 15:54
L7	1	temperature with control$4 same ((wafer adj chuck) (substrate adj support)) same electroplat$	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/05/11 15:54